

## PATENT ASSIGNMENT COVER SHEET

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 Stylesheet Version v1.2

EPAS ID: PAT3346225

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
TUNG LOK LI	04/02/2015
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	KAIXIN, INC.
<b>Street Address:</b>	22-28 TAI CHUNG ROAD
<b>Internal Address:</b>	8/F., HALE WEAL INDUSTRIAL BLDG.
<b>City:</b>	TSEUN WAN
<b>State/Country:</b>	CHINA
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	13929565
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Email:</b>	jtinker@winstead.com
<b>Correspondent Name:</b>	JEFFREY TINKER
<b>Address Line 1:</b>	2728 N. HARWOOD ST, SUITE 500
<b>Address Line 4:</b>	DALLAS, TEXAS 75201
<b>ATTORNEY DOCKET NUMBER:</b>	50641-P004C2
<b>NAME OF SUBMITTER:</b>	JEFFREY A. TINKER
<b>SIGNATURE:</b>	/Jeffrey A. Tinker/
<b>DATE SIGNED:</b>	05/08/2015
This document serves as an Oath/Declaration (37 CFR 1.63).	
<b>Total Attachments: 4</b>	
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**COMBINED ASSIGNMENT & DECLARATION  
FOR UTILITY OR DESIGN PATENT APPLICATION**

**ASSIGNMENT**

**THIS ASSIGNMENT**, made by Tung Lok LI (hereinafter referred to as Assignor), residing at 5B Cameron House, 40 Magazine Gap Road, The Peak, Hong Kong, PEOPLE'S REPUBLIC OF CHINA;

**WHEREAS**, Assignor has invented certain new and useful improvements in METHOD OF MANUFACTURING LEADLESS INTEGRATED CIRCUIT PACKAGES HAVING ELECTRICALLY ROUTED CONTACTS, set forth in a Patent application for Letters Patent of the United States, already filed on 27 June 2013 as U.S. Application No. 13/929,565; and

**WHEREAS**, Kaixin, Inc., a Corporation organized under and pursuant to the laws of China having its principal place of business at 8/F., Hale Weal Industrial Bldg., 22-28 Tai Chung Road, Tseun Wan, PEOPLE'S REPUBLIC OF CHINA (hereinafter referred to as Assignee), is desirous of acquiring the entire right, title and interest in and to said inventions and said Application for Letters Patent of the United States, and in and to any Letters Patent of the United States to be obtained therefore and thereon.

**NOW, THEREFORE**, in consideration of One Dollar (\$1.00) and other good and sufficient consideration, the receipt of which is hereby acknowledged, Assignor has sold, assigned, transferred and set over, and by these presents does sell, assign, transfer and set over, unto Assignee, its successors, legal representatives and assigns, the entire right, title and interest in and to the above-mentioned inventions and application for Letters Patent, and in and to any and all direct and indirect divisions, continuations and continuations-in-part of said application, and any and all Letters Patent in the United States and all foreign countries which may be granted therefore and thereon, and reissues, reexaminations and extensions of said Letters Patent, and all rights under the International Convention for the Protection of Industrial Property, the same to be held and enjoyed by Assignee, for its own use and benefit and the use and benefit of its successors, legal representatives and assigns, to the full end of the term or terms for which Letters Patent may be granted and/or extended, as fully and entirely as the

same would have been held and enjoyed by Assignor, had this sale and assignment not been made.

**AND** for the same consideration, Assignor hereby represents and warrants to Assignee, its successors, legal representatives and assigns, that, at the time of execution and delivery of these presents, except for any rights, titles and/or interests that have arisen to Assignee under law or that have already been transferred to Assignee, Assignor is the sole and lawful owner of the entire right, title and interest in and to the said inventions and application for Letters Patent above-mentioned, and that the same are unencumbered and that Assignor has good and full right and lawful authority to sell and convey the same in the manner herein set forth.

**AND** for the same consideration, Assignor hereby covenants and agrees to and with Assignee, its successors, legal representatives and assigns, that Assignor will sign all papers and documents, take all lawful oaths and do all acts necessary or required to be done for the procurement, maintenance, enforcement and defense of any Letters Patent and applications for Letters Patent for said inventions, without charge to Assignee, its successors, legal representatives and assigns, whenever counsel of Assignee, or counsel of its successors, legal representatives and assigns, shall advise: that any proceeding in connection with said inventions, or said Patent application for Letters Patent, or any proceeding in connection with any Letters Patent or applications for Letters Patent for said inventions in any country, including but not limited to interference proceedings, is lawful and desirable; or, that any division, continuation or continuation-in-part of any application for Letters Patent, or any reissue, reexamination or extension of any Letters Patent, to be obtained thereon, is lawful and desirable.

**AND** Assignor hereby requests the Commissioner for Patents and Trademarks to issue said Letters Patent of the United States to Assignee, as Assignee of said inventions and the Letters Patent to be issued thereon, for the sole use and benefit of Assignee, its successors, legal representatives and assigns.

**AND** Assignor acknowledges an obligation of assignment of this invention to Assignee at the time the invention was made.

**DECLARATION**

As a below named inventor, I hereby declare that:

This declaration is directed to the patent application entitled:

METHOD OF MANUFACTURING LEADLESS INTEGRATED  
CIRCUIT PACKAGES HAVING ELECTRICALLY ROUTED  
CONTACTS

the specification of which was filed on 27 June 2013 as Application No. 13/929,565.

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application, as amended 3 January 2014 and 28 March 2015.

I have reviewed and understand the contents of the above-identified application.

I am aware of the duty to disclose to the Office all information known to me to be material to patentability as defined in 37 C.F.R. 1.56.

I hereby acknowledge that any willful false statement made in this Declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

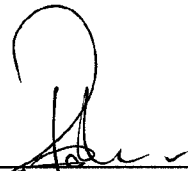
In the event that the filing date and/or Application No. are not entered above at the time I execute this document, and if such information is deemed necessary, I hereby authorize and request the attorneys/agent(s) at Winstead PC, P.O. Box 131851, Dallas, Texas 75313, to insert the filing date and/ or Application No. of said application into this document.

4/2/2015  
Date

4/2/15  
Tung Lok LI

Witness:

4/2/2015  
Date

  
Patrick Phun